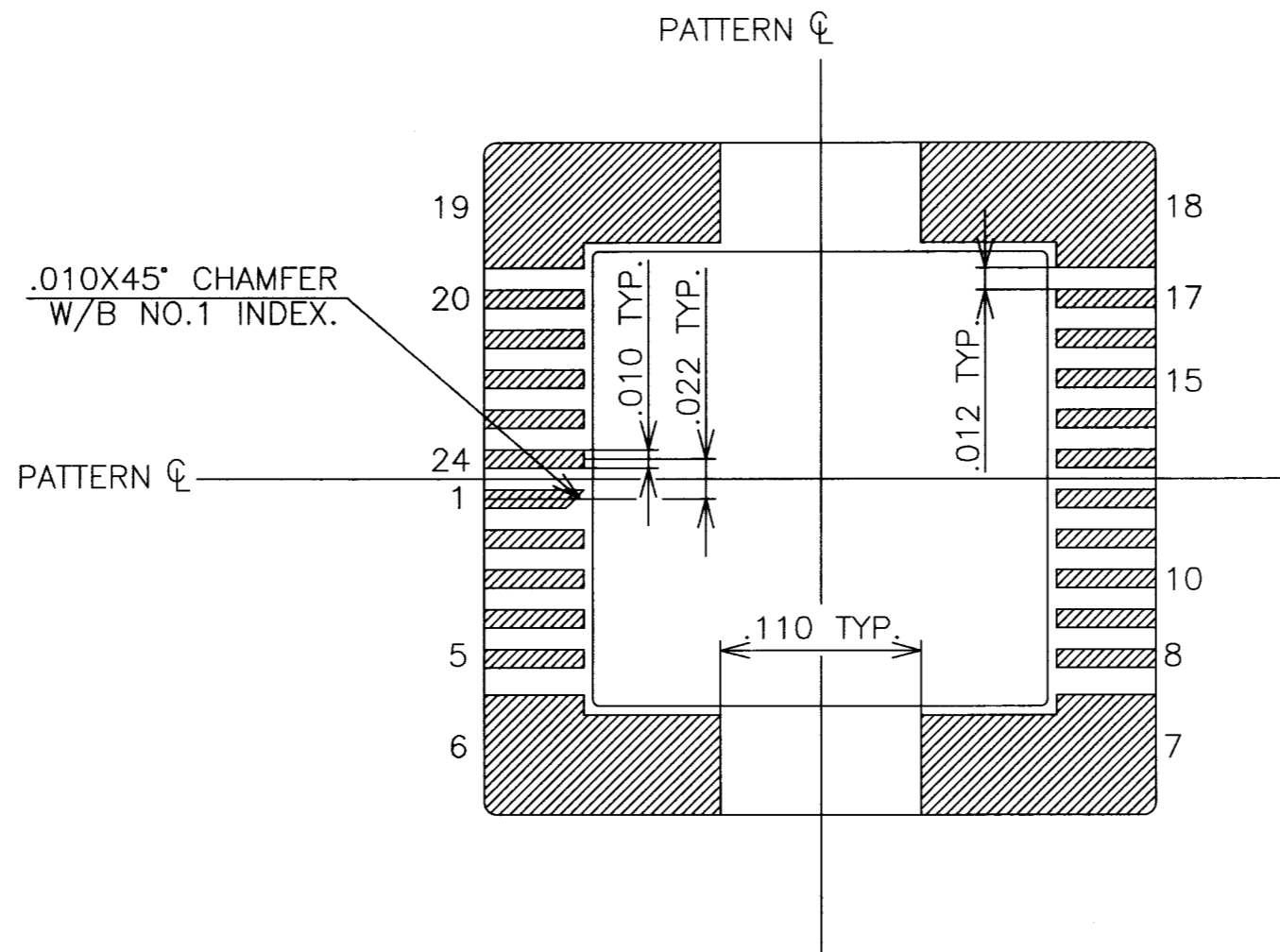


NOTES

- GOLD PLATING 60 MICRO INCHES MIN. THICKNESS OVER 100 MICRO INCHES NOMINAL THICKNESS OF NICKEL. UNLESS OTHERWISE SPECIFIED IN PURCHASE ORDER.
- DIE ATTACH PAD AND SEAL RING TO BE FLOATING FROM ANY PINS.
- LEAD RESISTANCE : 0.5 OHM MAX.

MODIFICATION					NAME	TOLERANCE	SB024L036-1				S=0
					24 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED	APPROVED	DATE	D=0
					SCALE 4 / 1	MATERIAL AS INDICATED	H.K	K.M		FEB.3.'81	
						±.005					
	△ REDRAWN : CONVERTED CAD DATA.	MAY.7.'01	T.S/H.K	SH.K/S.NI	H.SA	THIRD ANGLE PROJECTION	DRAWING NO.				SHEET
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	KYOCERA	KYOCERA CORPORATION				1 / 2
							KYOTO JAPAN				
							KD-S81036-A				



BONDING PATTERN

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						24 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	H.K	K.M		FEB.3.'81
						SCALE 10 / 1	MATERIAL	<i>Jomo. 2</i>	<i>S.K. 3/79</i>	<i>Rep. H. Sch</i>	
							THIRD ANGLE PROJECTION				
	△	REDRAWN : CONVERTED CAD DATA. CHANGED	MAY.7.'01	T.S/H.K	SH.K/S.NI	H.SA					
			DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN		DRAWING NO.	SHEET
										KD-S81036-A	2 / 2